



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

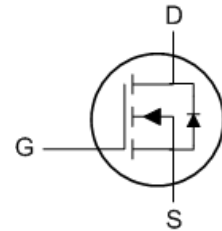
**Product Summary**

BVDSS	RDSON	ID
60V	8.2mΩ	98A

**Description**

The FKH6018A is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The FKH6018A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

**TO263 Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	60	V
$V_{GS}$	Gate-Source Voltage	±20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	98	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	62	A
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	11.5	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	9.2	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	300	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	125	mJ
$I_{AS}$	Avalanche Current	50	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	149	W
$P_D@T_A=25^\circ C$	Total Power Dissipation <sup>4</sup>	2.02	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	0.84	°C/W

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	60	---	---	V
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =30A	---	6.5	8.2	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2.5	---	4.5	V
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =48V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	5	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =30A	---	97	---	S
Q <sub>g</sub>	Total Gate Charge (10V)	V <sub>DS</sub> =48V , V <sub>GS</sub> =10V , I <sub>D</sub> =25A	---	35.5	---	nC
Q <sub>gs</sub>	Gate-Source Charge		---	8.6	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	15.9	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =30V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω, I <sub>D</sub> =30A	---	17.2	---	ns
T <sub>r</sub>	Rise Time		---	33.6	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	28.0	---	
T <sub>f</sub>	Fall Time		---	18.9	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz	---	1990	---	pF
C <sub>oss</sub>	Output Capacitance		---	400	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	180	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	80	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C	---	---	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =30A , dI/dt=100A/μs ,	---	11.9	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	4.6	---	nC

## Note :

- The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=50V,V<sub>GS</sub>=10V,L=0.1mH,I<sub>AS</sub>=50A
- The power dissipation is limited by 150°C junction temperature
- The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

Typical Characteristics

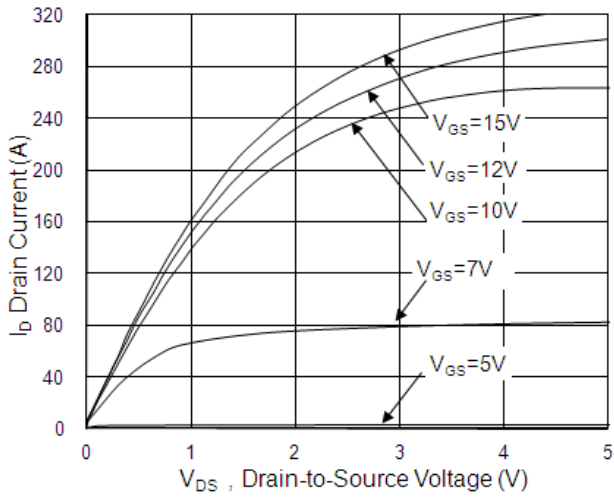


Fig.1 Typical Output Characteristics

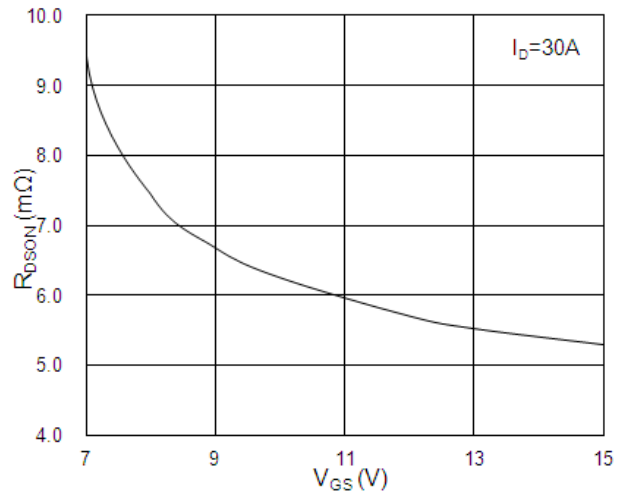


Fig.2 On-Resistance vs. G-S Voltage

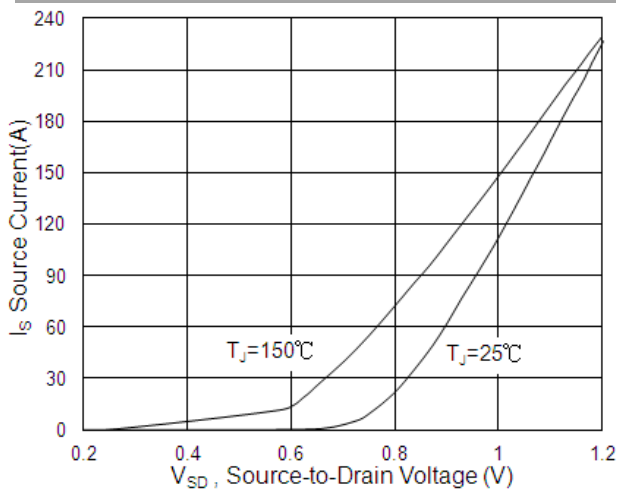


Fig.3 Source Drain Forward Characteristics

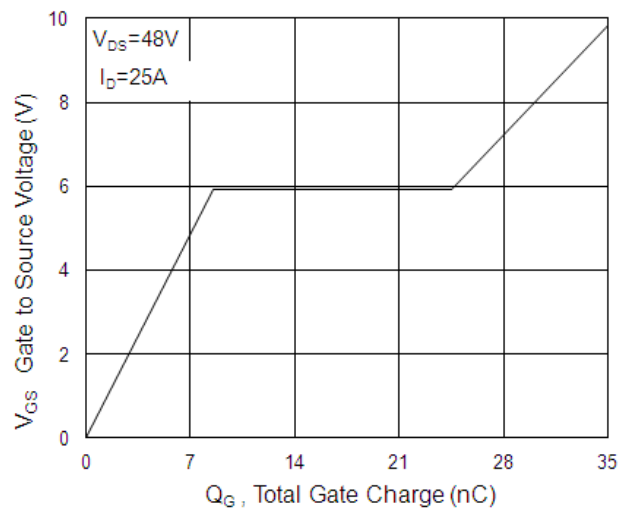


Fig.4 Gate-Charge Characteristics

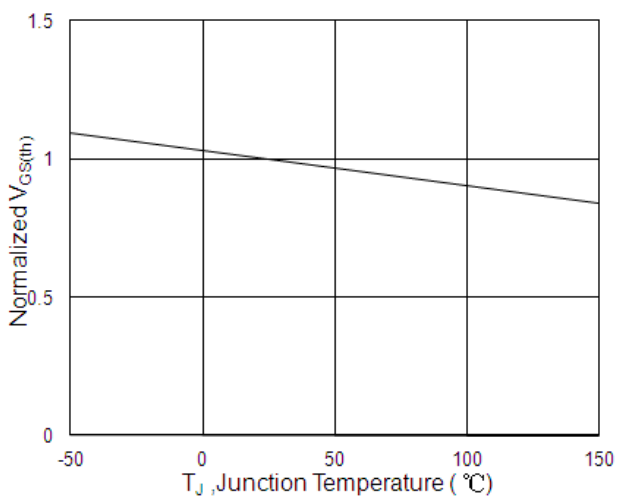


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

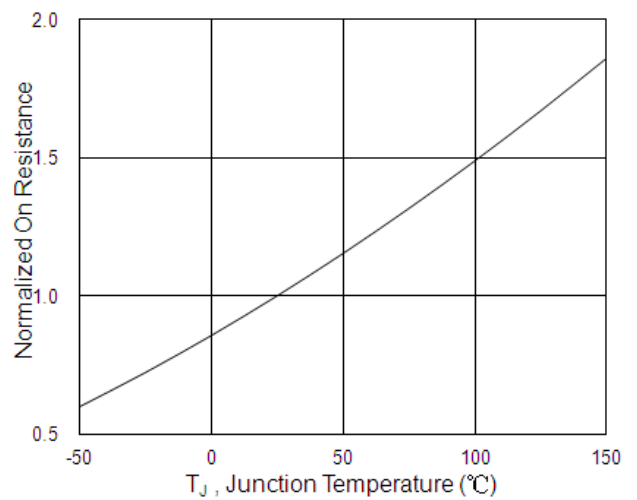


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

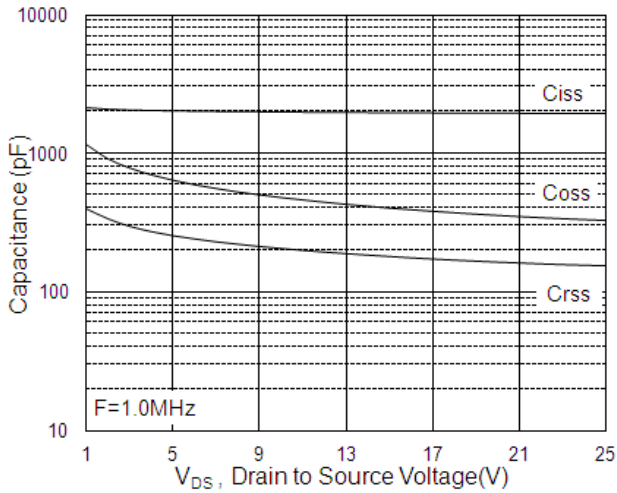


Fig.7 Capacitance

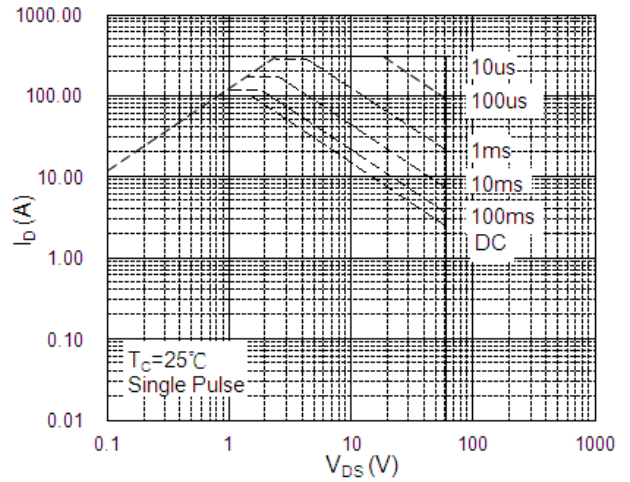


Fig.8 Safe Operating Area

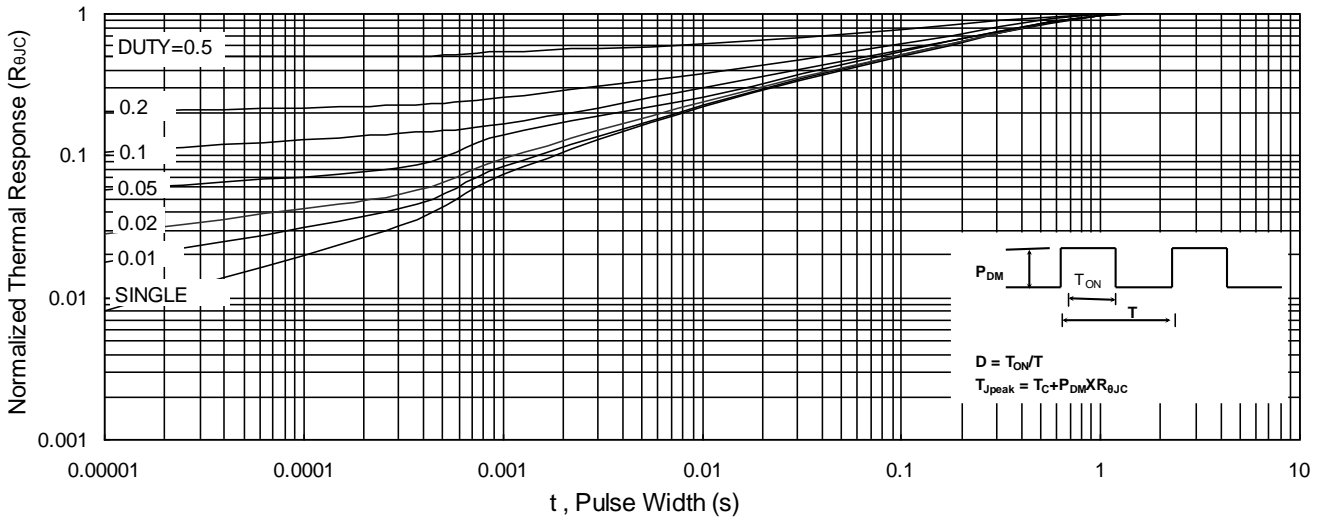


Fig.9 Normalized Maximum Transient Thermal Impedance

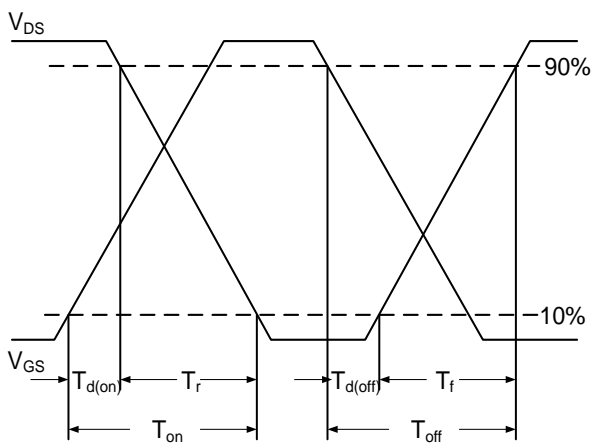


Fig.10 Switching Time Waveform

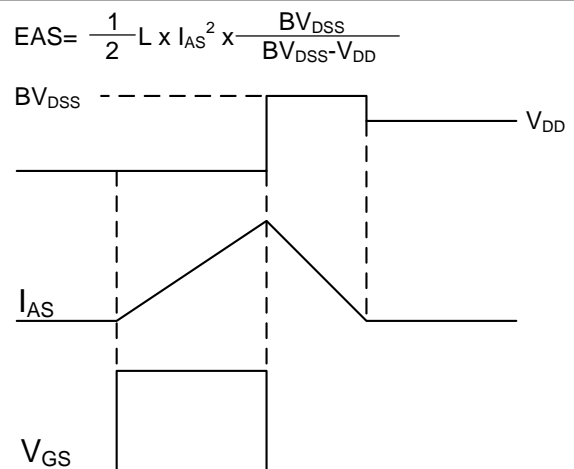
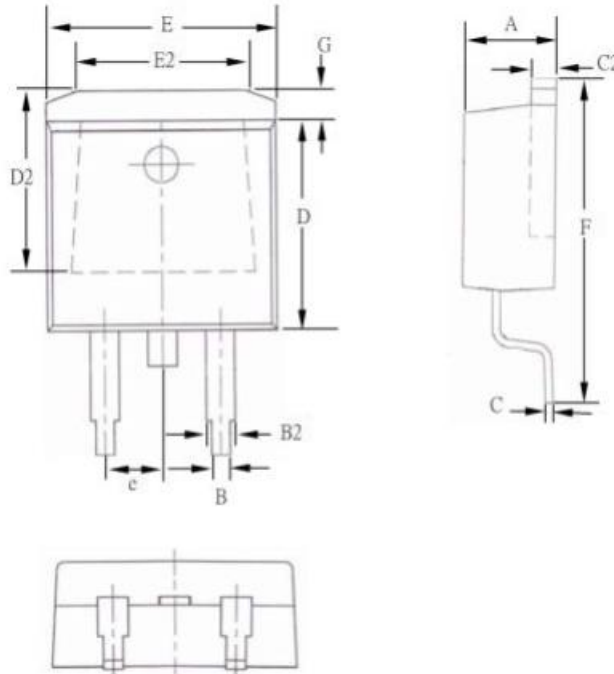


Fig.11 Unclamped Inductive Switching Waveform

## TO263 Package Outline Dimensions



SYMBOL	MILLIMETERS			INCHES		
	MIN	NOM		MIN	NOM	
A	4.06	—	4.83	0.160	—	0.190
B	0.51	—	0.99	0.020	—	0.039
B2	1.14	—	1.78	0.045	—	0.070
C	0.34	—	0.74	0.013	—	0.029
C2	1.14	—	1.65	0.045	—	0.065
D	8.38	—	9.65	0.330	—	0.380
D2	6.86	—	7.86	0.270	—	0.309
E	9.65	—	10.67	0.380	—	0.420
E2	6.22	—	7.40	0.245	—	0.291
F	13.08	—	15.50	0.515	—	0.610
G	0.68	—	1.68	0.027	—	0.066
e	—	2.54	—	—	0.100	—